

IN THE SPECIFICATION

Please replace the paragraph beginning on page 2, line 3, with the following amended paragraph:

However, until recently no thin-film heaters on aluminum or aluminum alloy substrates have been reported. Aluminum and its alloys have a relatively high coefficient of expansion (22-26 ppm/K) compared to the insulating layers used for steel substrates which are in most cases enamel-based insulators. Insulating layers commonly used for steel substrates cannot be used for aluminum (alloy) substrates. Mismatched thermal expansion coefficients result in cracking of the film when the heating element is exposed to temperature cycles. Furthermore, in order to apply these insulators, the precursors are applied on a suitable substrate, after which the precursor has to be cured at high temperatures above 650 °C in order to obtain a suitable insulating layer. These high curing temperatures exceed or are near to the melting temperature of aluminum (660 °C) and its alloys. Therefore, these materials are not suitable as electrically insulating layers for aluminum substrates.